

86749 Nickel/Copper Fabric Tape

Innovative **Technology** for a **Connected** World



NI/CU POLYESTER CONDUCTIVE FABRIC TAPE

Laird Technologies' Conductive Fabric Tape 86749 offers exceptional conformability and conductivity for dynamic flex applications. It is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions. The 86749 is a halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

FEATURES **FROHS**

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of < 0.06 Ω/□ provides excellent conductivity
- Shielding effectiveness of >62 dB across a wide spectrum of frequencies

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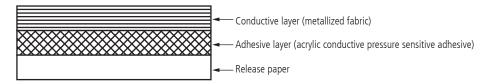
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86749 Nickel/Copper Fabric Tape

| Item | Unit | Value | Test Method |
|---|-------------|---|-------------|
| Thickness | mm | 0.060 mm ± 0.01 | - |
| Peel Adhesion | Kgf / 25 mm | >0.8 | PSTC 101* |
| Shear Adhesion | | | |
| at R.T. | Hrs | >72 | PSTC 107# |
| at 80°C | Hrs | >5 | PSTC 107# |
| Tensile Strength | Kgf / 25 mm | >7 | |
| Operation Temperature | °C | 0-80 | |
| Surface Resistivity (Fabric Side) | Ω/□ | <0.06 | ASTM F390 |
| Z-axial Resistance | Ω | <0.04 | |
| Shielding Effectiveness+ | | | ASTM D4935 |
| at 100 MHz | dB | 62 | |
| at 1GHz | dB | 68 | |
| Package Dimensions (Max. Width: 1000 mm) | М | W: Dimension by Customer Spec L: Standard Length of 20 M | |
| Shelf Life (Under 23°C/65% R.H.) | | Six Months | |

^{*:}Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

- 1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
- To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified.
 A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
- 3. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

Mouser Electronics

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